



UPBLED470A

HIGH BRIGHTNESS BLUE LED

PRODUCT PREVIEW

Microsemi's high brightness UPBLED470A product offers impressive brightness with industry leading thermal resistivity. These products deliver superior thermal performance that keep junction temperatures low with a remarkable package thermal resistivity of 110 degrees C/Watt. The blue packages also deliver a very wide viewing angle able to easily integrate into optical lenses. The Optomite package performs extremely well under extreme temperature conditions with less wavelength shift and intensity degradation seen by many competitors.

IMPORTANT: For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>

ABSOLUTE MAXIMUM RATINGS AT 25° C (UNLESS OTHERWISE SPECIFIED)

Parameters	Symbol	Value	Unit DC
Forward Drive Current	I_F	30	mA
Peak Forward Current	I_{FP}	100	mA
LED Operating Junction Temperature	T_J	-40 to +150	°C
Reverse Voltage	V_R	8	V
Power Dissipation	P_D	125	mW
Operating Temperature	T_{OPR}	-40 to +125	°C
Storage Temperature	T_S	-45 to +150	°C
Electrostatic Discharge	ESD	1000	V
ESD classification		Class 2	
Solder Reflow peak Temperature (Solder 10")		225	°C

THERMAL CHARACTERISTICS (UNLESS OTHERWISE SPECIFIED)

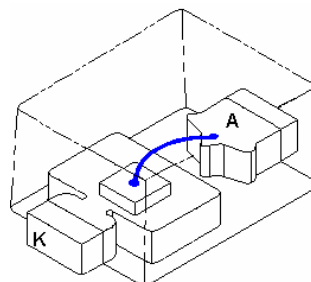
Thermal Resistance	Symbol	Value	Units
Junction-to Soldering Point	$R_{\theta JS}$	110	°C/W

KEY FEATURES

- Low Thermal Resistance
- Rugged Optomite 0603 package
- High Brightness
- Wide viewing angle

APPLICATIONS/BENEFITS

- Mobile Phone Keypad
- Panel, button, switch indicators.
- Backlighting
- Signage
- Signals and Marker Lights



For operation of these LEDs in pulse mode applications, devices may be used in conjunction with the Microsemi LX1992LED Drivers



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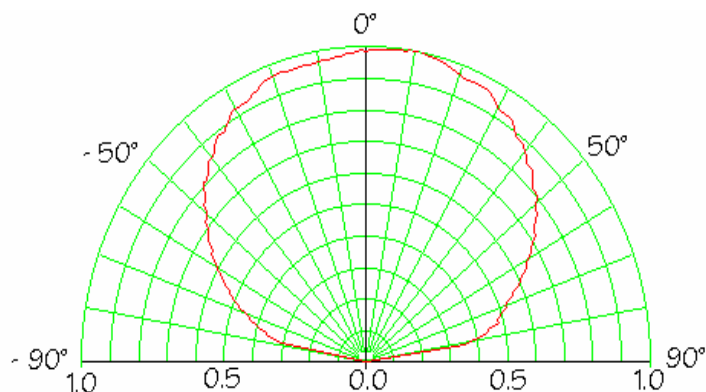
ELECTRICAL PARAMETERS @ 25°C & ID=20 mA (unless otherwise specified)

Characteristic	Symbol	Test Conditions	Min	Typ.	Max	Units
Radiant Intensity	I_E	DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 mA		700 950 1,300		$\mu\text{W/sr}$
Luminous Intensity	I_V	DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 mA	35	50 75 100		mcd
Dominant Wavelength	λ_{DOM}	DC Drive Current = 20 mA		468		nm
Peak Wavelength	λ_{PK}	DC Drive Current = 20 mA		460		nm
Chrom x Chrom y		DC Drive Current = 20 mA		.125 .09		
Angle Coverage to 50% points	$\alpha_{1/2}$	DC Drive Current = 20 mA to 50mA	140			deg.
Radiant Flux	Φ_E	DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 m		2 2.8 4		mW
Luminous Flux	Φ_V	DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 m		190 250 350		lm
Forward Voltage	V_F	DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 mA		3.5 3.9 4.5	3.9	V
Reverse Leakage Current	I_R	Reverse Voltage = 5 V			10	μA

- Change in Radiant Intensity with temperature $-1.4 \mu\text{W/sr}/^\circ\text{C}$ ($25^\circ\text{C} < \text{temp} < 85^\circ\text{C}$)
- Change in Radiant Intensity with temperature $0.7 \mu\text{W/sr}/^\circ\text{C}$ ($25^\circ\text{C} < \text{temp} < -40^\circ\text{C}$)

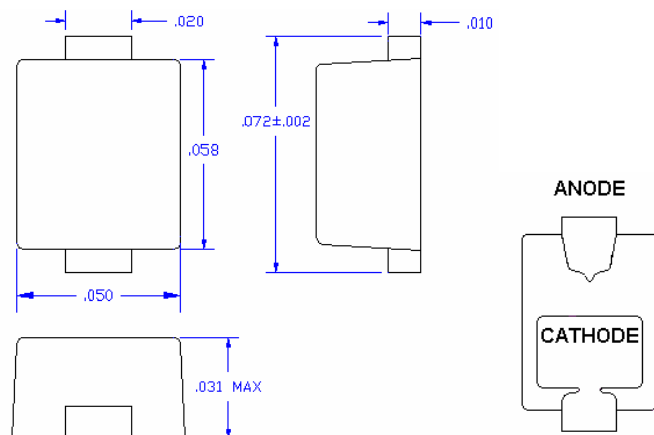
DIRECTIVITY

Polar Plot of Angular Intensity



Relative Angular Intensity

Typical UPBLED470A

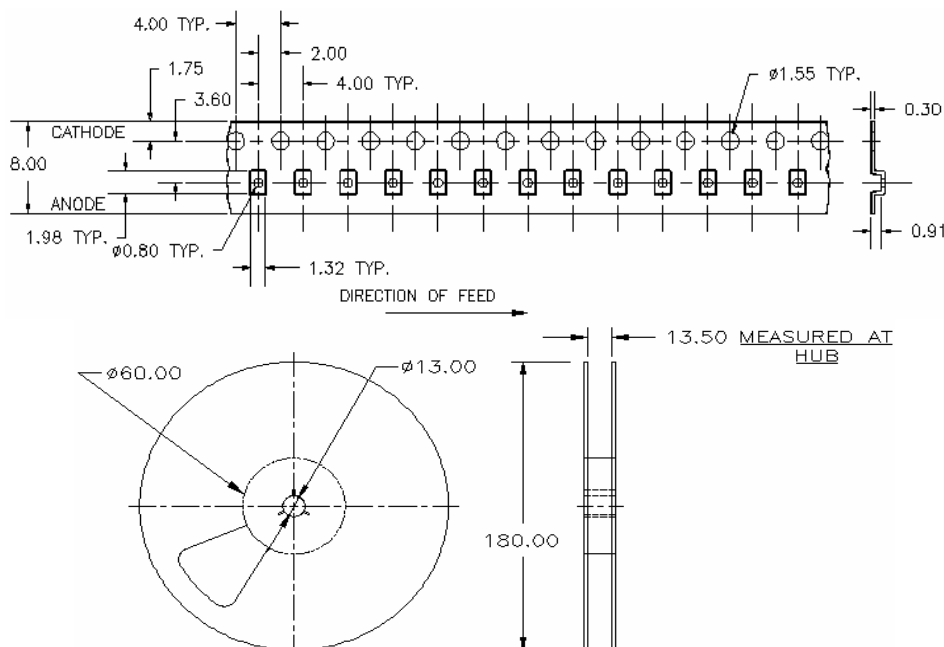

BOTTOM VIEW

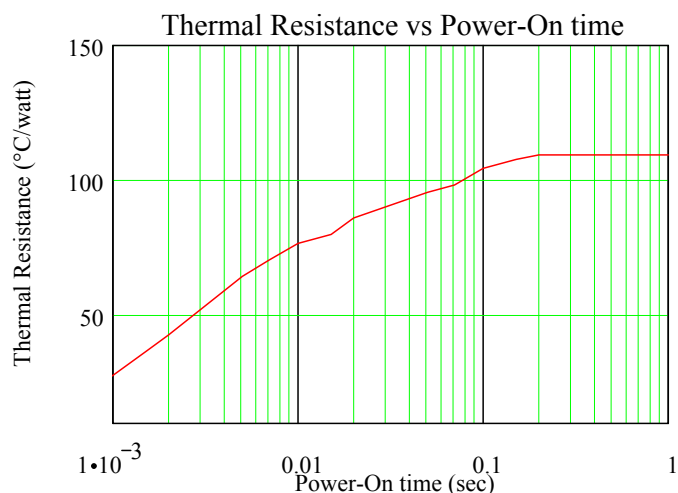
Notes:

- Anode is identified by observing the underside of the LED.
- (Anode is the smaller of the two base pads)
- Mount to circuit board using 60/40 Pb/Sn or equivalent.
- Maximum solder melt exposure temperature is 225°C for 10 seconds.

TAPE AND REEL
3,000 units/reel

Notes: Dimensions is shown in metric.

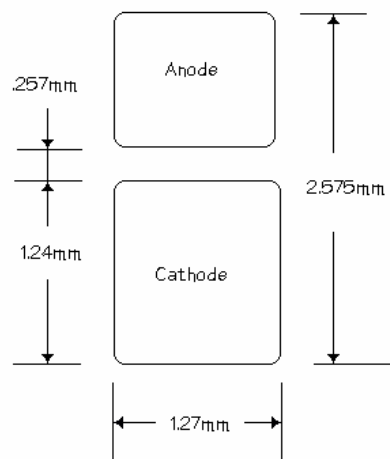




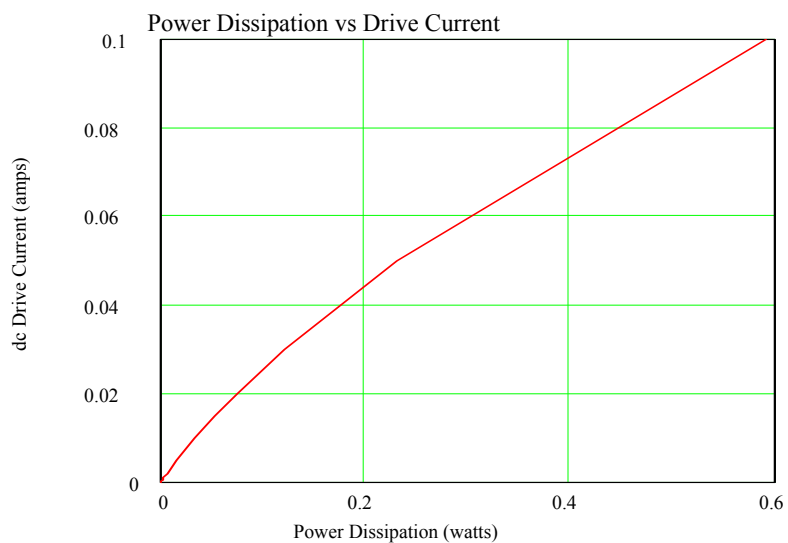
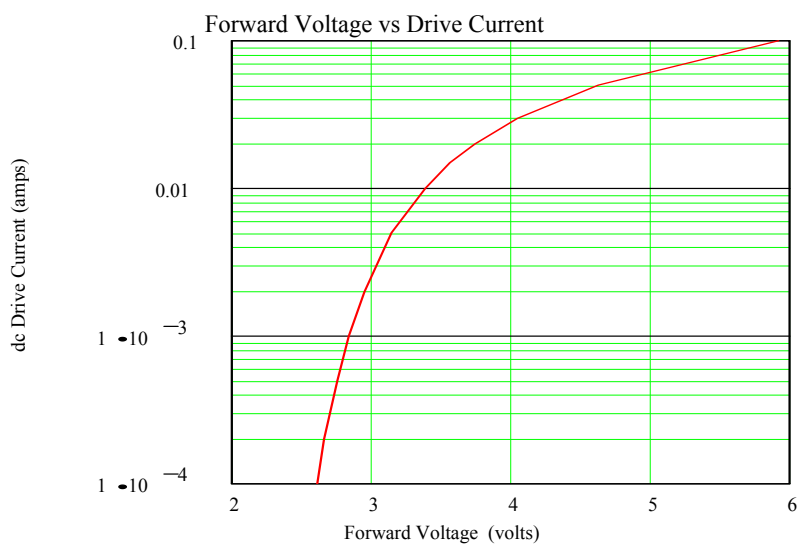
Steady State Thermal Resistance Junction-to-Optomite base metal ~ 110°C/W

Thermal time constant ~ 20 mS (@ 0.632 x R_{0max}).

Steady state temperature at ~ 500 mS.



Mounting footprint, Copper (note: Silver plating will enhance Luminous Intensity)





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CALCULATION FOR SAFE OPERATION ABOVE 20 ma dc:

The power dissipation must be held at a level to maintains the junction below the maximum specified operating temperature.

Duty cycle control may be used to establish the safe operating condition using a train of pulses.

LED Junction temperature may be calculated by use of the following:

$$T_J := T_{Case} + V_F \cdot I_{Dpk} \left[\frac{t_p \cdot R_{\theta JS}}{\tau} + \left(1 - \frac{t_p}{\tau} \right) \cdot Z_{\theta \tau + t_p} - Z_{\theta \tau} + Z_{\theta tp} \right]$$

T_{Case} is at a specified temperature. V_F and I_{Dpk} values are read off graph of forward voltage vs drive current. t_p and τ are set by the on-time and pulse period of the drive circuit. Thermal Impedances (Z_{θ}) and Thermal resistance (R_{θ}) values are read from Thermal Impedance graph.

Conversion of 1931 x y coordinates to 1960 u v coordinates:

$$u = 4x/(-2x + 12y + 3), \quad v = 6y/(-2x + 12y + 3)$$

Conversion of 1960 u v coordinates to 1931 x y coordinates:

$$x = 3u/(2u - 8v + 4), \quad y = 2v/(2u - 8v + 4).$$

* UPBLED-470A SPICE MODEL

```
.model UPBLED-470A D(Is=1E-30 N=1.923 Rs=32 Ikf=42.04 Eg=3.6 Cjo=63.87p
+      M=.1513 Vj=2.02 Fc=.5 Isr=1.3m Nr=3.4Meg Bv=12 Ibv=369.5u
+      Tt=432.8n Xti=5)
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